

RF AMPLIFIER

MODEL *TM5325*

Available as: TM5325, 4 Pin TO-8 (T4)
 TN5325, 4 Pin Surface Mount (SM3)
 FP5325, 4 Pin Flatpack (FP4)
 BX5325, Connectorized Housing (H1)
 PN5325, 4 Pin Surface Mount (SM11)

Features

- Low Noise Figure: 3.0 dB Typical
- High Output Power: +24 dBm Typical
- Operating Temp. - 55 °C to +85 °C
- Environmental Screening Available

Specifications

CHARACTERISTIC	TYPICAL Ta= 25 °C	MIN/MAX Ta = -55 °C to +85 °C
Frequency	5-125 MHz	10-100 MHz
Gain (dB)	20.5	20.5 + 1.0
Power @ 1 dB Comp. (dBm)	+24	+22.5 Min.
Reverse Isolation (dB)	-24	-23 Max.
VSWR In	1.70:1	2.2:1 Max.
Out	1.35:1	2.0:1 Max.
Noise Figure (dB)	3.0	3.5 Max.
Power Vdc	+12	+12 Min.
mA	85	95

Typical Intermodulation Performance at 25 ° C

Second Order Harmonic Intercept Point +58 dBm (Typ.)
 Second Order Two Tone Intercept Point +52 dBm (Typ.)
 Third Order Two Tone Intercept Point +40 dBm (Typ.)
 (Intermod values are measured at midband)

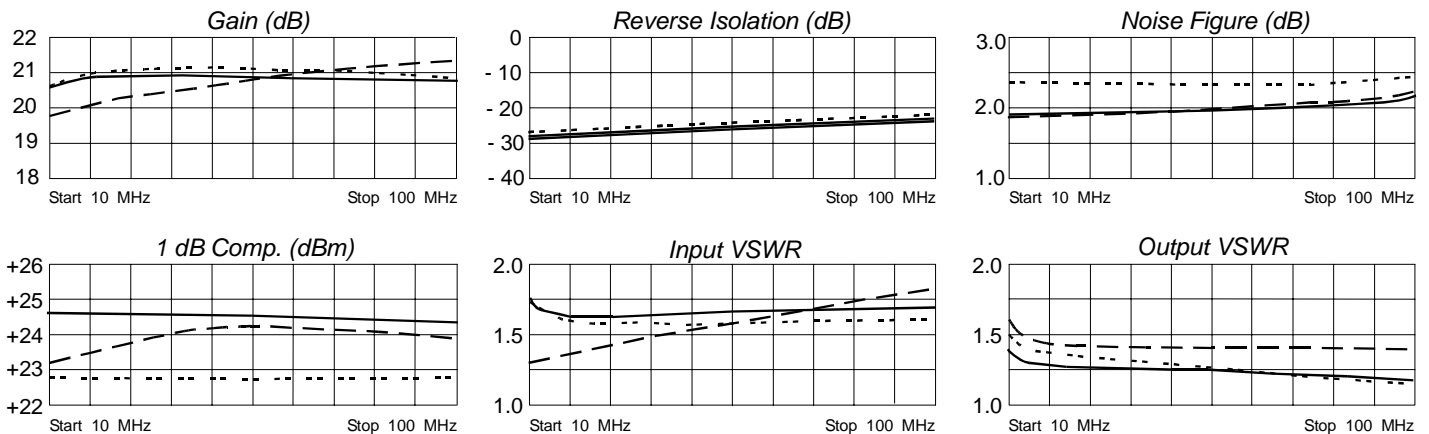
Maximum (NO DAMAGE) Ratings

Ambient Operating Temperature -55°C to + 100 °C
 Storage Temperature -62°C to + 125 °C
 Case Temperature + 125 °C
 DC Voltage + 15 Volts
 Continuous RF Input Power + 18 dBm
 Short Term RF Input Power 50 Milliwatts (1 Minute Max.)
 Maximum Peak Power 0.5 Watt (3 μsec Max.)

Note: Care should always be taken to effectively ground the case of each unit.
 Guaranteed when tested in a 50 ohm circuit.

Revision: April 21, 2026
 ECN: Updated NF value from 3 dB to 3.5 dB

Typical Performance Data



Linear S-Parameters

FREQ. MHz	S11		S21		S12		S22	
	Mag	Deg	Mag	Deg	Mag	Deg	Mag	Deg
5	.35	- 32	10.28	-157	.05	-159	.27	-27
10	.27	- 28	10.95	-171	.05	-174	.16	-32
50	.23	- 36	11.12	161	.06	151	.11	- 3
100	.26	- 68	11.10	139	.06	127	.10	-10
150	.32	-106	10.87	115	.07	103	.06	-29